

CLAIMS

What is claimed is:

1. A semiconductor package, comprising:
 - a substrate having a first side for disposing a plurality of conductive traces thereon, and a second side for forming a plurality of electrical connection terminals thereon;
 - 5 at least one chip attached to the first side of the substrate and electrically connected to the conductive traces;
 - 10 at least one passive device attached to the first side of the substrate and electrically connected to the conductive traces;
 - 15 a flash-proof device attached to the first side of the substrate and formed with a cavity for receiving the chip and the passive device therein, wherein a distance in elevation from a top side of the flash-proof device to the first side of the substrate is made to be slightly greater than a depth of a molding cavity of a mold used in a molding process; and
 - 20 an encapsulant for encapsulating the chip, the passive device, the flash-proof device and the substrate, wherein the second side of the substrate is exposed to outside of the encapsulant.
2. The semiconductor package of claim 1, wherein the flash-proof device is attached to the substrate by an elastic adhesive.
- 20 3. The semiconductor package of claim 1, wherein the flash-proof device is attached to the substrate by a thermally conductive adhesive.

4. The semiconductor package of claim 1, wherein the flash-proof device is further formed with a plurality of vias, which allow a molding compound used for forming the encapsulant to flow therethrough.
5. The semiconductor package of claim 1, wherein a plurality of step-like recesses are formed on edges of the top side of the flash-proof device.
6. The semiconductor package of claim 1, wherein the flash-proof device has an outer sidewall thereof adjacent to a side edge of the substrate.
7. The semiconductor package of claim 1, wherein the flash-proof device has an outer sidewall thereof aligned with a side edge of the substrate.
- 10 8. The semiconductor package of claim 1, wherein the top side of the flash-proof device is exposed to outside of the encapsulant.
9. The semiconductor package of claim 1, wherein a plurality of ground traces are formed on the conductive traces at positions corresponding to the flash-proof device, for attaching the flash-proof device to the ground traces by using an electrically conductive adhesive.
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